

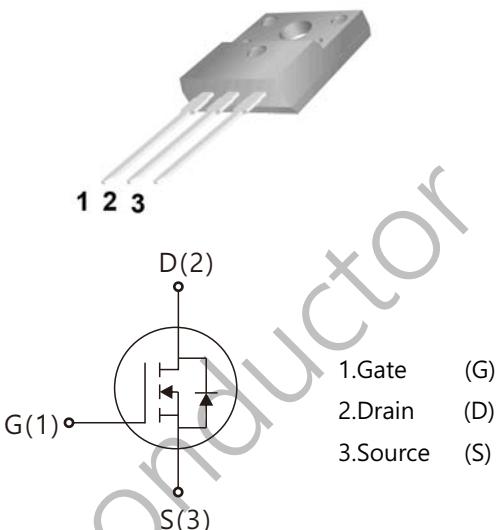


WGF10N65SE

Features:

- Low Intrinsic Capacitances.
- Excellent Switching Characteristics.
- Extended Safe Operating Area.
- Unrivalled Gate Charge : $Q_g = 35\text{nC}$ (Typ.).
- $V_{DSS} = 650\text{ V}$, $I_D = 10\text{A}$
- $R_{DS(on)} : 0.9\ \Omega$ (Max) @ $V_G = 10\text{V}$
- 100% Avalanche Tested

TO -220F



Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	650	V
I_D	Drain Current	$T_j = 25^\circ\text{C}$	10
		$T_j = 100^\circ\text{C}$	6.7
V_{GSS}	Gate-Source Voltage	30	V
E_{AS}	Single Pulse Avalanche Energy (note1)	380	mJ
I_{AR}	Avalanche Current (note2)	10	A
P_D	Power Dissipation ($T_j = 25^\circ\text{C}$)	65	W
T_j	Junction Temperature(Max)	150	°C
T_{stg}	Storage Temperature	-55~+150	°C
TL	Maximum lead temperature for soldering purpose, 1/8' from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance,Junction to Case	-	2.4	°C/W
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	-	62.5	°C/W

Electrical Characteristics (Ta=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	I _D =250μA , V _{GS} =0	650	-	-	V
△BV _{DSS} / △T _J	Breakdown Voltage Temperature Coefficient	I _D =250μA , Reference to 25°C	-	0.67	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =650V, V _{GS} =0V	-	-	10	μA
		V _{DS} =520V, T _J =125°C			100	
I _{GSSF}	Gate-body leakage Current, Forward	V _{GS} =+30V, V _{DS} =0V	-	-	100	nA
I _{GSSR}	Gate-body leakage Current, Reverse	V _{GS} =-30V, V _{DS} =0V	-	-	-100	
On Characteristics						
V _{GS(TH)}	Date Threshold Voltage	I _D =250μA, V _{DS} =V _{GS}	2	-	4	V
R _{DS(ON)}	Static Drain-Source On-Resistance	I _D =5.0A, V _{GS} =10V	-	0.8	0.9	Ω
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V , V _{GS} =0 , f=1.0MHz	-	1500	-	pF
C _{oss}	Output Capacitance		-	194	-	
C _{rss}	Reverse Transfer Capacitance		-	18	-	
Switching Characteristics						
T _{d(on)}	Turn-On Delay Time	V _{DD} =325V , I _D =10A R _G =25Ω (Note 3,4)	-	23		nS
T _r	Turn-On Rise Time			15		
T _{d(off)}	Turn-Off Delay Time		-	90		
T _f	Turn-Off Rise Time		-	30		
Q _g	Total Gate Charge	V _{DS} =520V, V _{GS} =10V , I _D =10A (Note 3,4)	-	35		nC
Q _{gs}	Gate-Source Charge			7	-	
Q _{gd}	Gate-Drain Charge			18	-	
Drain-Source Diode Characteristics and Maximum Ratings						
I _s	Max. Diode Forward Current	-		--	10	A
I _{SM}	Max. Pulsed Forward Current	-		--	40	
V _{SD}	Diode Forward Voltage	I _D =10A	-	-	1.4	V
T _{rr}	Reverse Recovery Time	I _S =10A, V _{GS} =0V diF/dt=100A/μs (Note 3)	-	320	-	nS
Q _{rr}	Reverse Recovery Charge		-	4.2	-	μC

Notes : 1, L=0.5mH, IAS= 10A, VDD=50V, RG=25Ω , Starting TJ =25°C

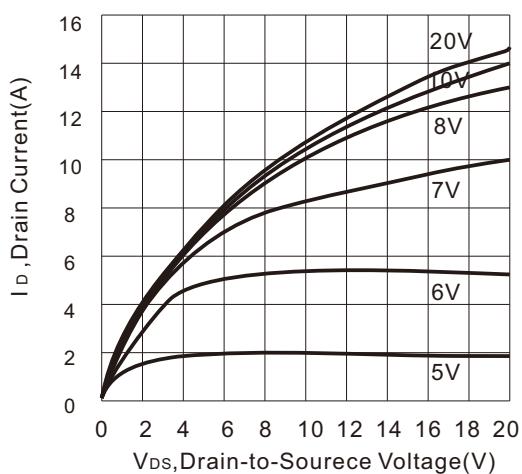
2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

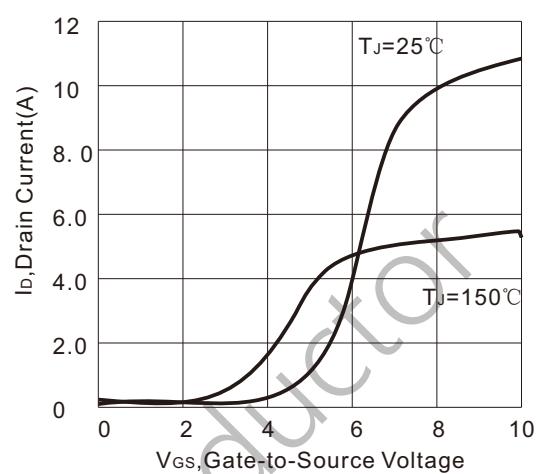
4, Essentially Independent of Operating Temperature

Typical Characteristics

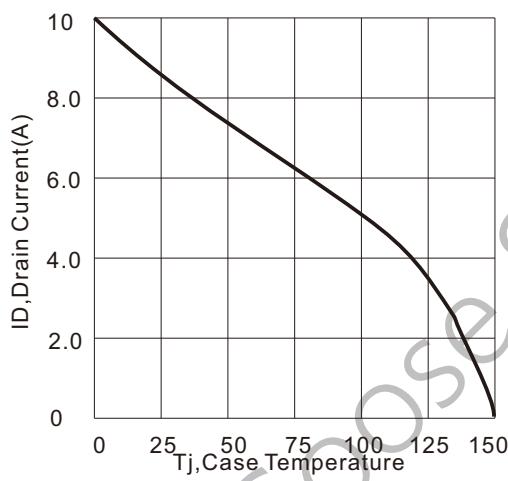
Output Characteristics



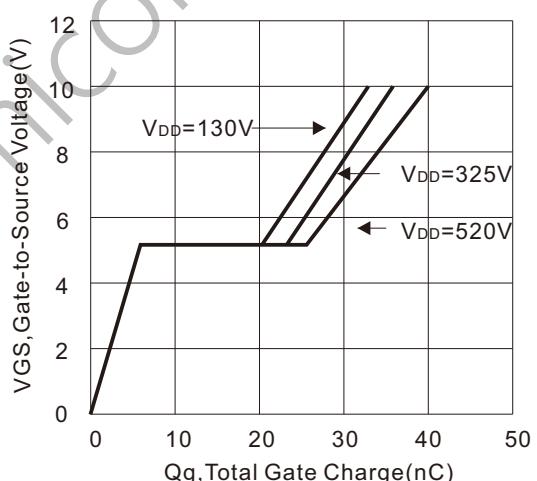
Transfer Characteristics



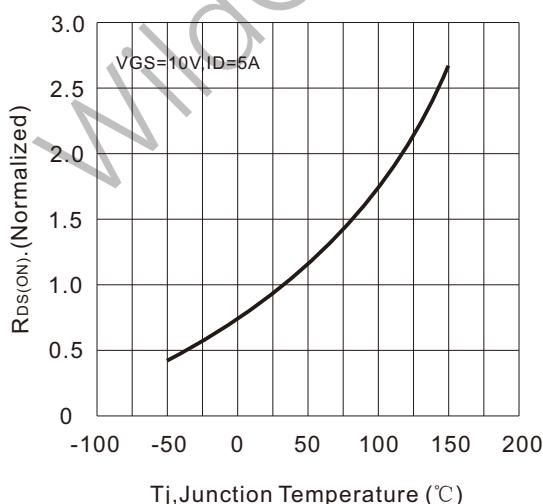
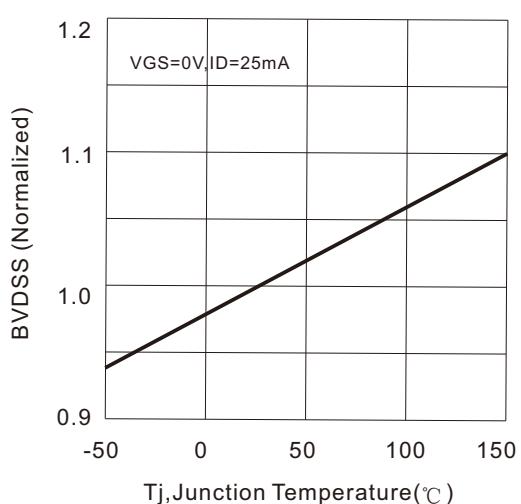
Drain Current VS. Temperature



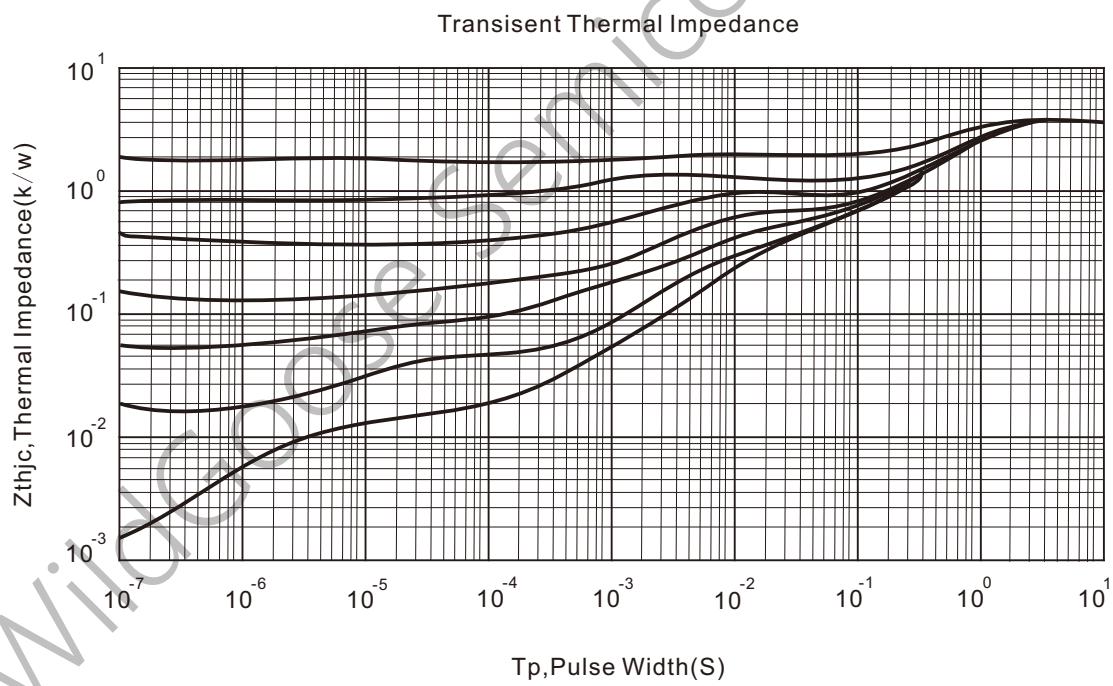
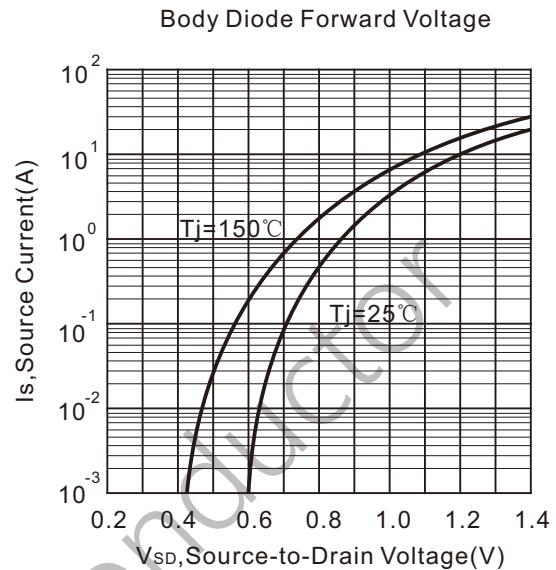
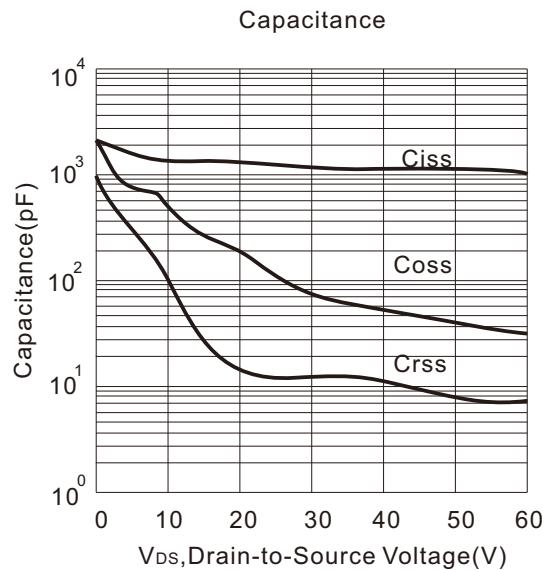
Gate Charge



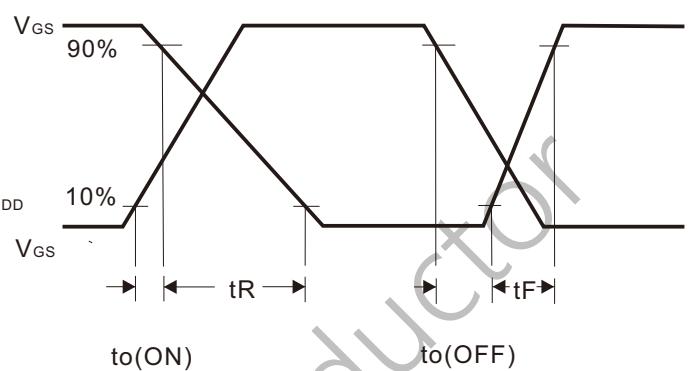
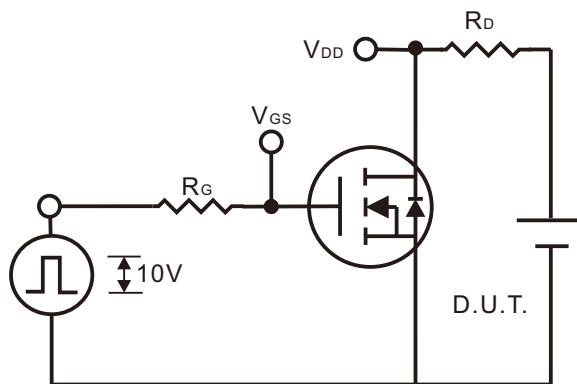
On-Resistance vs. Junction Temperature

BV_{DSS} Variation VS. Temperature

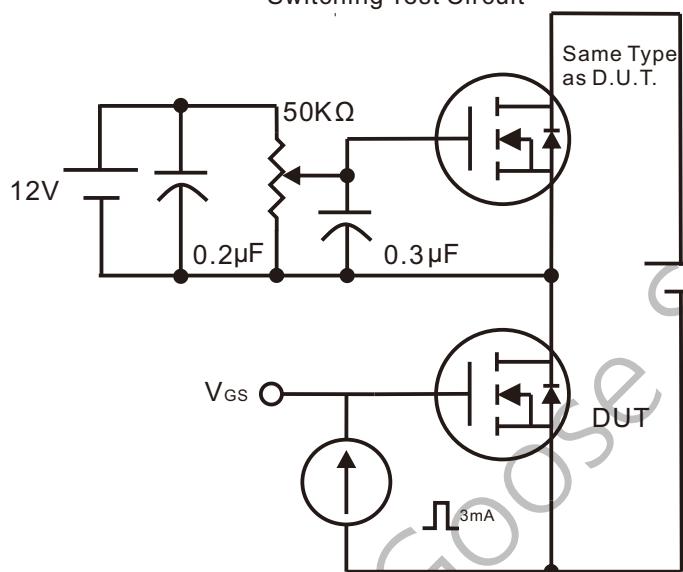
Typical Characteristics (Continued)



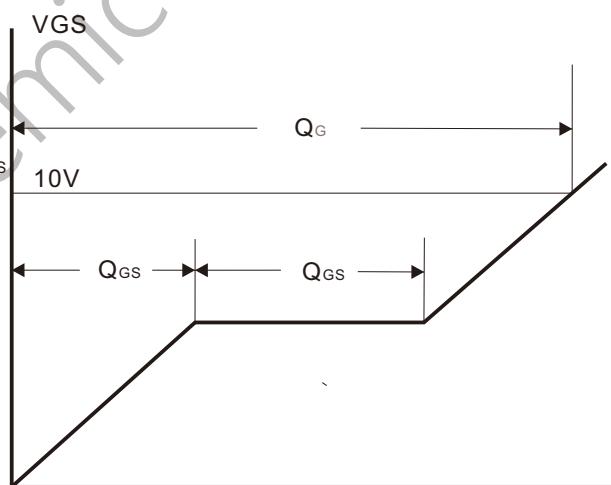
Gate Charge Test Circuit & Waveform



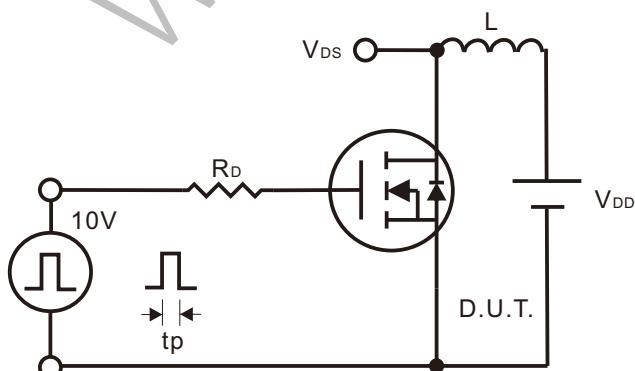
Switching Test Circuit



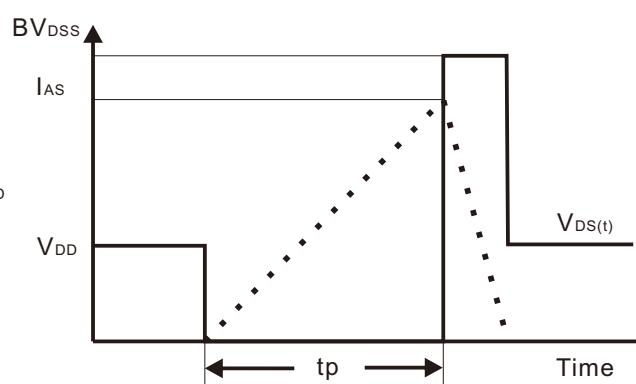
Switching Waveforms



Gate Charge Test Circuit

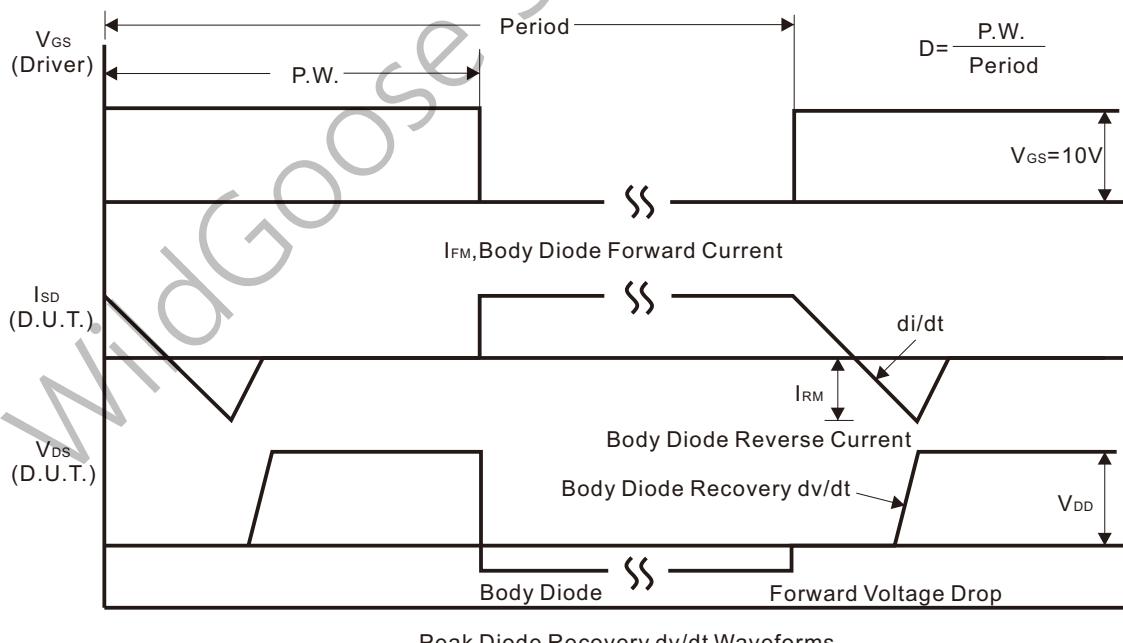
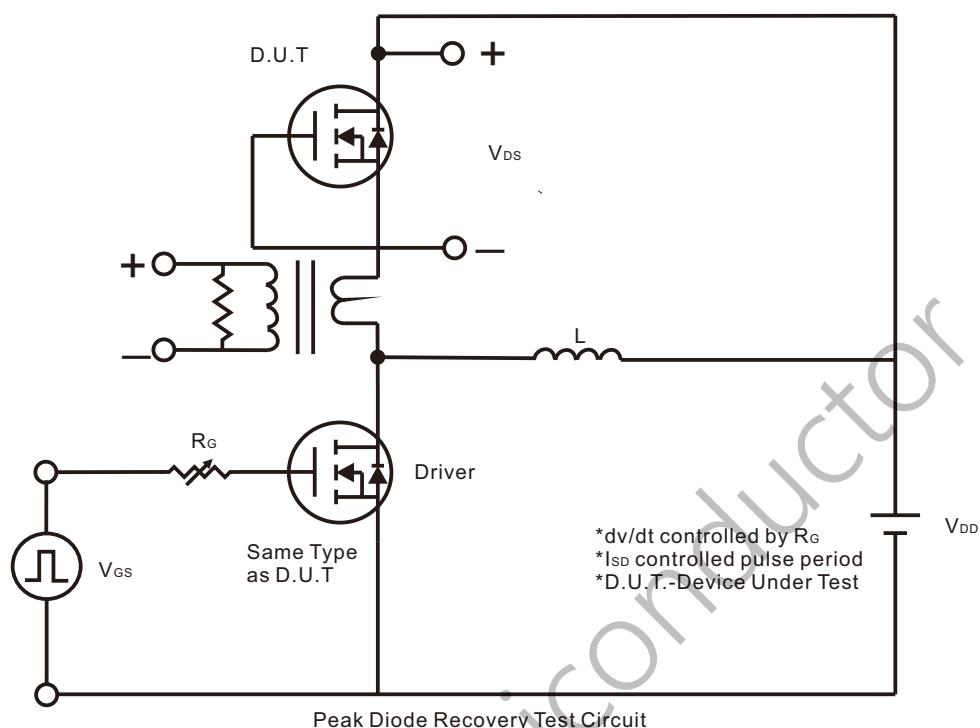


Gate Charge Waveform



Unclamped Inductive Switching Test Circuit

Peak Diode Recovery dv/dt Test Circuit & Waveform



Peak Diode Recovery dv/dt Waveforms

Package Dimension

TO-220F

Unit: mm

